

SOT1463-1

wafer level chip-scale package, 46 bumps

27 April 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP46
Package style descriptive code	WLCSP (wafer level chip-size package)
Package style suffix code	NA (not applicable)
Mounting method type	S (surface mount)
Issue date	2-3-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.77	-	1.8	1.83	mm
E	package width	1.11	-	1.14	1.17	mm
A	seated height	0.255	-	0.28	0.305	mm
A ₂	package height	0.18	-	0.2	0.22	mm
e	nominal pitch	-	-	0.15	-	mm
n ₂	actual quantity of termination	-	-	46	-	



2. Package outline

WLSCP46: wafer level chip-scale package; 46 bumps; 1.80 x 1.14 x 0.28 mm

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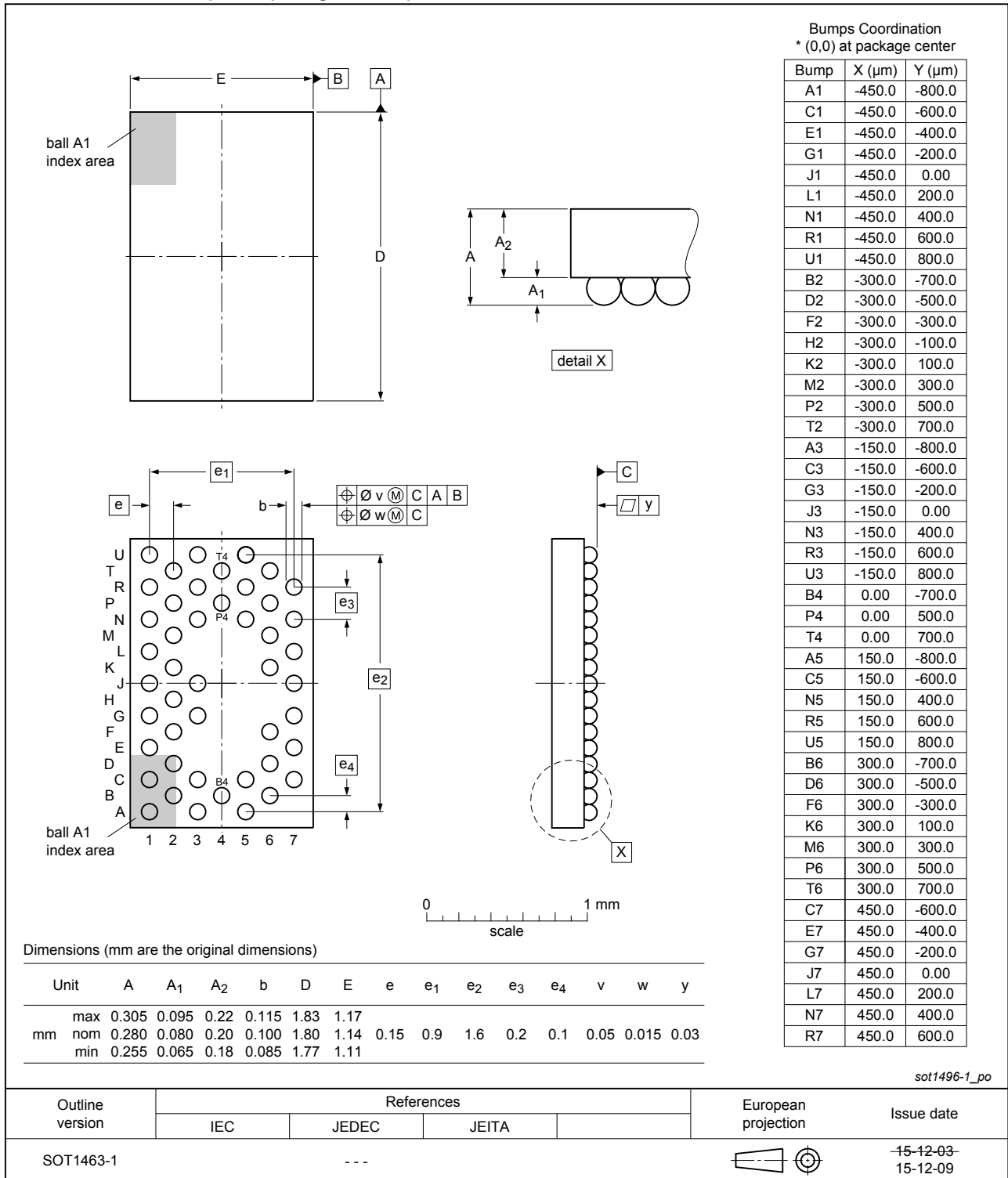


Fig. 1. Package outline WLSCP46 (SOT1463-1)

3. Legal information

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